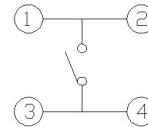
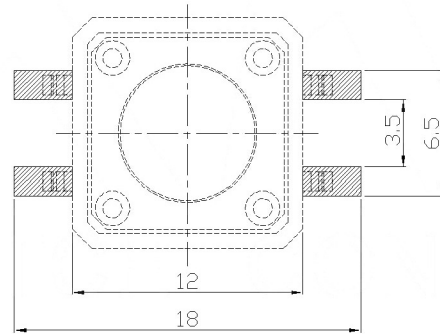
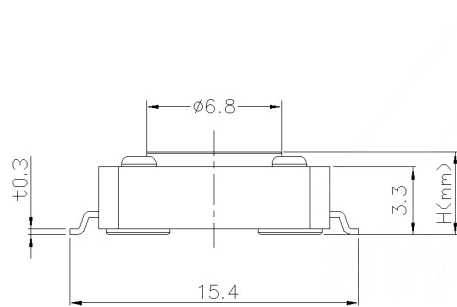


CIRCUIT DIAGRAM



Code-X	H	Code-X	H
A	4.3	O	11.0
B	4.5	P	11.5
C	5.0	Q	12
D	5.5	R	12.5
E	6.0	S	13.0
F	6.5	T	13.5
G	7.0	U	14.0
H	7.5	V	15.0
I	8.0	W	15.5
J	8.5	X	16
K	9.0	Y	17
L	9.5	Z	18
M	10.0	19	19
N	10.5		

P.C.B MOUNTING PATTERN DIMENSION
The following soldering patterns are recommended for reflow soldering



SPECIFICATION

Contact Rating: 50mA, 12V DC
 Contact Resistance: 100mΩ max
 Insulation Resistance: 100MΩ min. 500V DC
 Dielectric Strength: 250V AC/1minute
 Travel: 0.25mm
 Operating Temp: -30°C ~ +85°C
 Storage Temp: -30°C ~ +80°C

PAPT NO	TS-1103S-X-X
Operating Force	B: 160g C: 260g
Height	Code-X

ITEM	PAPT NMF	TER. NO	QTY	MATERIAL	FINISHING	REMARK
⑤	Terminal	4		Brass (0.30t)	Plating silvering	
④	Contact	1		F. ag/Sus	Natural	
③	Base	1		Pa46		
②	Cover	1		Spcc	Plating Nickel	
①	Keystake	1		Pa46		

MARK	DESCRIPTION	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES
Δ X					units: mm
Δ X					tolerance: X.X ±0.2mm
Δ X					X.XX ±0.1mm
MARK					X.XXX ±0.05mm

DSND	DATE	SCALE: N/A	MODEL TYPE:
DWN	DATE	VIEW:	TACT SWITCH
CHKD	DATE	UNIT: mm	PART NO.:
APPD	DATE	SIZE: A4	DWG NO.:
			TS-1103S-X-X
			WEIGHT SHEET REVISION
			1.0g 1/1 A0

Kosod Technology Co., Ltd.